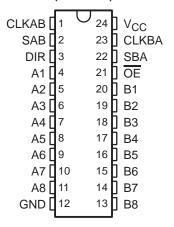
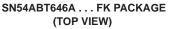
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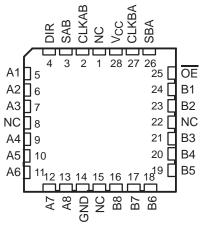
- Typical V<sub>OLP</sub> (Output Ground Bounce) <1 V at  $V_{CC} = 5$  V,  $T_A = 25^{\circ}$ C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Ioff Supports Partial-Power-Down Mode Operation

SN54ABT646A...JT OR W PACKAGE SN74ABT646A...DB, DGV, DW, NS, NT, OR PW PACKAGE (TOP VIEW)



- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- **ESD Protection Exceeds JESD 22** 
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)





NC - No internal connection

## description/ordering information

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT646A devices.

#### ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – NT	Tube	SN74ABT646ANT	SN74ABT646ANT	
	2010 DW	Tube	SN74ABT646ADW	ADT040A	
	SOIC – DW	Tape and reel	SN74ABT646ADWR	ABT646A	
	SOP - NS	Tape and reel	SN74ABT646ANSR	ABT646A	
-40°C to 85°C	SSOP - DB	- DB Tape and reel SN74ABT64		AB646A	
	TOOOD DW	Tube	SN74ABT646APW	A DO 40 A	
	TSSOP – PW	Tape and reel	SN74ABT646APWR	AB646A	
	TVSOP - DGV	Tape and reel	SN74ABT646ADGVR	AB646A	
	CDIP – JT	Tube	SNJ54ABT646AJT	SNJ54ABT646AJT	
–55°C to 125°C	CFP – W	Tube	SNJ54ABT646AW	SNJ54ABT646AW	
	LCCC - FK	Tube	SNJ54ABT646AFK	SNJ54ABT646AFK	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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### description/ordering information(continued)

Output-enable  $(\overline{OE})$  and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus receives data when  $\overline{OE}$  is low. In the isolation mode ( $\overline{OE}$  high), A data can be stored in one register and/or B data can be stored in the other register.

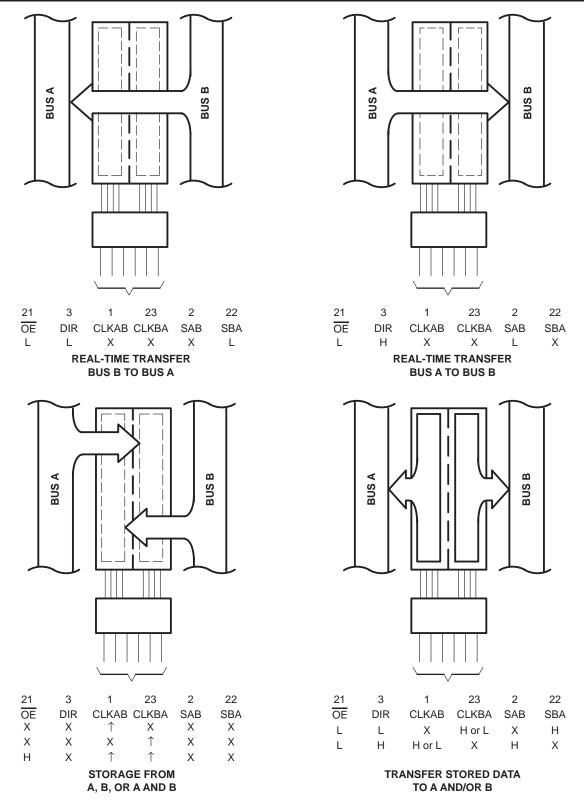
When an output function is disabled, the input function still is enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

These devices are fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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Pin numbers shown are for the DB, DGV, DW, JT, NS, NT, PW, and W packages.

Figure 1. Bus-Management Functions

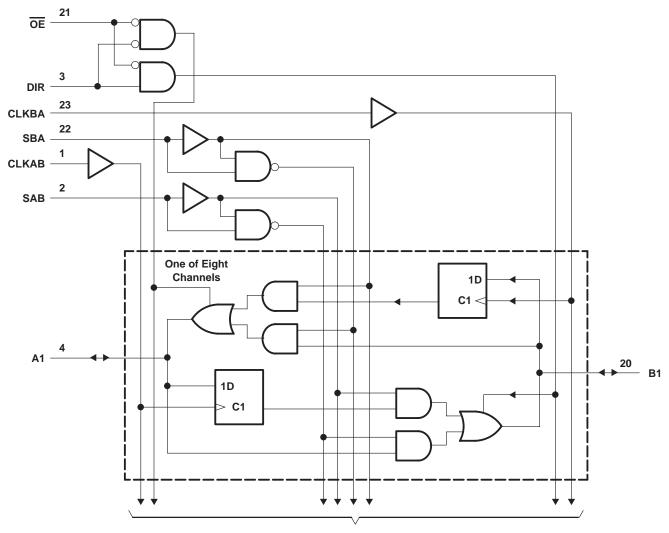


#### **FUNCTION TABLE**

		INP	UTS			DATA	A I/Os	
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Χ	Х	Х	Input	Unspecified <sup>†</sup>	Store A, B unspecified <sup>†</sup>
Х	X	X	$\uparrow$	X	Χ	Unspecified <sup>†</sup>	Input	Store B, A unspecified <sup>†</sup>
Н	Х	1	$\uparrow$	Х	Х	Input	Input	Store A and B data
Н	X	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Χ	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

<sup>†</sup> The data-output functions can be enabled or disabled by various signals at  $\overline{OE}$  and DIR. Data-input functions always are enabled, i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

## logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DB, DGV, DW, JT, NS, NT, PW, and W packages.



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT646A	96 mA
SN74ABT646A	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DB package	63°C/W
(see Note 2): DGV package	86°C/W
(see Note 2): DW package	46°C/W
(see Note 2): NS package	65°C/W
(see Note 3): NT package	67°C/W
(see Note 2): PW package	88°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-3.

# recommended operating conditions (see Note 4)

		SN54ABT646A		SN74AB	T646A	LINUT
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		8.0	V
VI	Input voltage	0	VCC	0	VCC	V
loh	High-level output current		-24		-32	mA
loL	Low-level output current		48		64	mA
Δt/Δν	Input transition rise or fall rate		5		5	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54ABT646A		SN74ABT646A		
PA	ARAMETER	TEST COI	NDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT
٧ıK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
.,		V <sub>C</sub> C = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		.,
VOH		V 45V	$I_{OH} = -24 \text{ mA}$	2			2				V
		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -32 mA	2*					2		
\/ - ·		V 45V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V
V <sub>hys</sub>					100						mV
1.	Control inputs	V 55V.V	V CND			±1		±1		±1	
II .	A or B ports $V_{CC} = 5.5 \text{ V}, \text{ V}_{I}$		ACC or GMD			±100		±100		±100	μΑ
lozH <sup>‡</sup>	‡	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			10§		10§		10§	μΑ
l <sub>OZL</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-10§		-10§		-10§	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>C</sub> C = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
Io¶		V <sub>C</sub> C = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high			250		250		250	μΑ
Icc		$I_{O} = 0$ ,	Outputs low			30		30		30	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			250		250		250	μΑ
∆lcc <sup>#</sup>	<i>‡</i>	V <sub>CC</sub> = 5.5 V, One Other inputs at V <sub>C</sub>	input at 3.4 V, C or GND			1.5		1.5		1.5	mA
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			7						pF
C <sub>io</sub>	A or B ports	$V_0 = 2.5 \text{ V or } 0.5$	V		12						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN54ABT646A				
		V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT
		MIN	MAX			
fclock	Clock frequency		125		125	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	4		4		ns
t <sub>su</sub>	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3.5		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	1.5		1.5		ns



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> The parameters IOZH and IOZL include the input leakage current.

<sup>§</sup> This data-sheet limit may vary among suppliers.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.

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# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN74ABT646A					
		V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT	
		MIN	MAX				
fclock	Clock frequency		125		125	MHz	
t <sub>W</sub>	Pulse duration, CLK high or low	4		4		ns	
t <sub>su</sub>	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns	
th	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns	

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

				SN54ABT646A					
PARAMETER	FROM (INPUT)	TO (OUTPUT)		V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MAX	UNIT	
			MIN	TYP	MAX				
f <sub>max</sub>			125			125		MHz	
<sup>t</sup> PLH	CLIVDA au CLIVAD	A av D	2.2	4	5.1	2.2	6.7		
t <sub>PHL</sub>	CLKBA or CLKAB	A or B	1.7	4	5.1	1.2	6.7	ns	
<sup>t</sup> PLH	A - :: B	D A	1.5	3	4.3	1.5	5	ns	
t <sub>PHL</sub>	A or B	B or A	1.5	3.3	4.6	1.5	5.6		
<sup>t</sup> PLH	040 004	D on A	1.5	4	5.7	1.5	7.8	ns	
t <sub>PHL</sub>	SAB or SBA†	B or A	1.5	3.6	4.9	1.5	6.2		
<sup>t</sup> PZH	<del></del> <del>OE</del>	A D	1.5	4.3	5.3	1.5	7		
<sup>t</sup> PZL	OE OE	A or B	3	5.8	8	3	10.5	ns	
<sup>t</sup> PHZ	ŌĒ	A D	1.5	3.5	5.8	1	7.3		
t <sub>PLZ</sub>	OE OE	A or B	1.5	3	4	1.5	5.7	ns	
<sup>t</sup> PZH	DID	A D	1.5	4.5	5.7	1.5	7.3		
tPZL	DIR	A or B	2.5	6.5	9	2.5	11	ns	
t <sub>PHZ</sub>	DIR	A or B	1.5	3.8	6.5	1	9		
<sup>t</sup> PLZ	DIK	AUIB	1.5	3.8	4.7	1.2	6.7	ns	

<sup>†</sup>These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

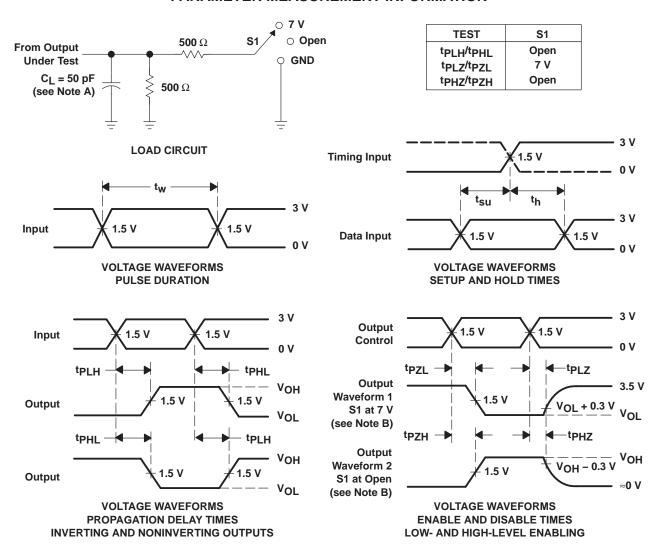
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX	]		
f <sub>max</sub>			125			125		MHz
t <sub>PLH</sub>	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.6	20
t <sub>PHL</sub>	CLKBA OF CLKAB	A OF B	1.7	4	5.1	1.7	5.6	ns
t <sub>PLH</sub>	A an D	D on A	1.5	3	4.3	1.5	4.8	
t <sub>PHL</sub>	A or B	B or A	1.5	3.3	4.6	1.5	5.4	ns
t <sub>PLH</sub>	SAB or SBA†	D on A	1.5	4	5.1	1.5	6.5	ns
t <sub>PHL</sub>	SAR OL SRVI	B or A	1.5	3.6	4.9	1.5	5.9	
<sup>t</sup> PZH	ŌĒ	A D	1.5	4.3	5.3	1.5	6.3	
t <sub>PZL</sub>	OE	A or B	3	5.8	7.4	3	8.8	ns
<sup>t</sup> PHZ	ŌĒ	A on D	1.5	3.5	4.5	1.5	5	
t <sub>PLZ</sub>	OE	A or B	1.5	3	4	1.5	4.5	ns
<sup>t</sup> PZH	DID	A on D	1.5	4.5	5.7	1.5	6.7	
t <sub>PZL</sub>	DIR	A or B	2.5	6.5	9	2.5	9.5	ns
<sup>t</sup> PHZ	DIR	A or B	1.5	3.8	5	1.5	5.7	ns
t <sub>PLZ</sub>	DIK	AUID	1.5	3.8	4.7	1.5	6	115

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.



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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

#### PACKAGE OPTION ADDENDUM



i.com 4-Mar-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9457702Q3A	ACTIVE	LCCC	FK	28	1	None	Call TI	Level-NC-NC-NC
5962-9457702QKA	ACTIVE	CFP	W	24	1	None	Call TI	Level-NC-NC-NC
5962-9457702QLA	ACTIVE	CDIP	JT	24	1	None	Call TI	Level-NC-NC-NC
SN74ABT646ADBLE	OBSOLETE	SSOP	DB	24		None	Call TI	Call TI
SN74ABT646ADBR	ACTIVE	SSOP	DB	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ABT646ADGVR	ACTIVE	TVSOP	DGV	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ABT646ADW	ACTIVE	SOIC	DW	24	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74ABT646ADWR	ACTIVE	SOIC	DW	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74ABT646ANSR	ACTIVE	SO	NS	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ABT646ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ABT646APW	ACTIVE	TSSOP	PW	24	60	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ABT646APWLE	OBSOLETE	TSSOP	PW	24		None	Call TI	Call TI
SN74ABT646APWR	ACTIVE	TSSOP	PW	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54ABT646AFK	ACTIVE	LCCC	FK	28	1	None	Call TI	Level-NC-NC-NC
SNJ54ABT646AJT	ACTIVE	CDIP	JT	24	1	None	Call TI	Level-NC-NC-NC
SNJ54ABT646AW	ACTIVE	CFP	W	24	1	None	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

None: Not yet available Lead (Pb-Free).

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

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<sup>(2)</sup> Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.



# **PACKAGE OPTION ADDENDUM**

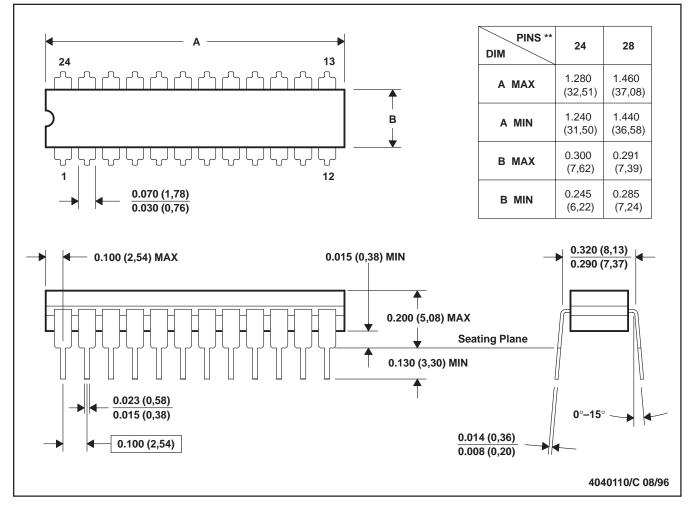
4-Mar-2005

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by to Customer on an annual basis.

### JT (R-GDIP-T\*\*)

#### 24 LEADS SHOWN

#### **CERAMIC DUAL-IN-LINE**

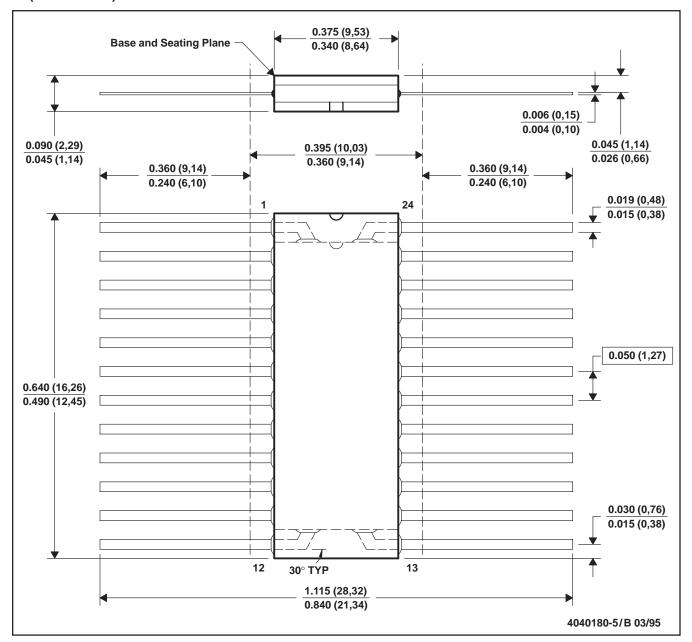


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

### W (R-GDFP-F24)

#### **CERAMIC DUAL FLATPACK**



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
  - E. Index point is provided on cap for terminal identification only.



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

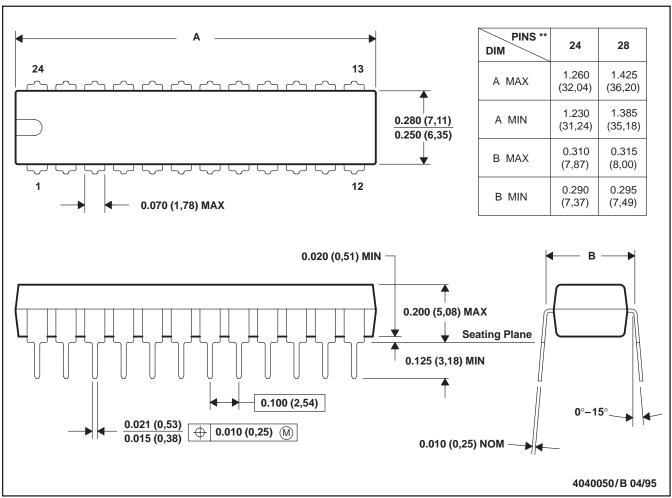
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



### NT (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

#### **24 PINS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

## DGV (R-PDSO-G\*\*)

### 24 PINS SHOWN

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

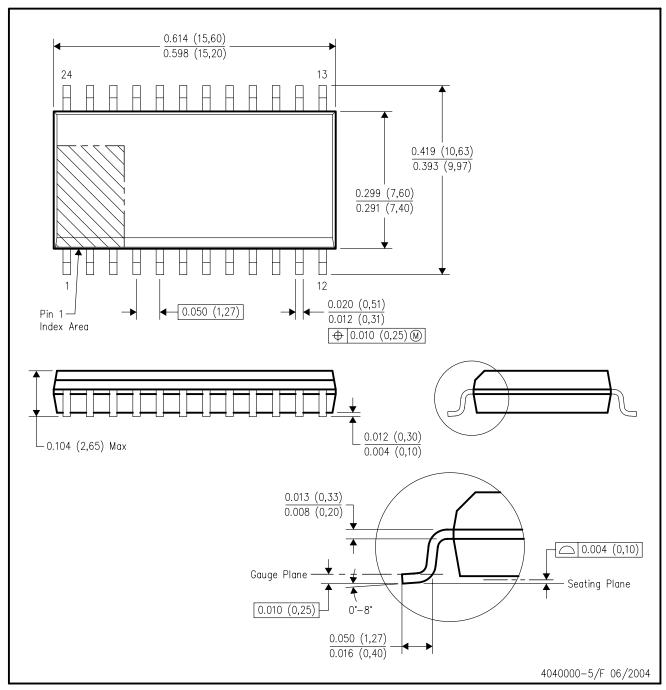
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

# DW (R-PDSO-G24)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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